



www.ti.com 29-Apr-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MSP430FR5962IPMR	Active	Production	LQFP (PM) 64	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5962
MSP430FR5962IPNR	Active	Production	LQFP (PN) 80	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5962
MSP430FR5962IRGZR	Active	Production	VQFN (RGZ) 48	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5962
MSP430FR5962IZVWR	Active	Production	NFBGA (ZVW) 87	1000 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	FR5962
MSP430FR5964IPMR	Active	Production	LQFP (PM) 64	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5964
MSP430FR5964IPNR	Active	Production	LQFP (PN) 80	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5964
MSP430FR5964IRGZR	Active	Production	VQFN (RGZ) 48	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5964
MSP430FR5964IZVWR	Active	Production	NFBGA (ZVW) 87	1000 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	FR5964
MSP430FR5992IPMR	Active	Production	LQFP (PM) 64	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5992
MSP430FR5992IPNR	Active	Production	LQFP (PN) 80	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5992
MSP430FR5992IRGZR	Active	Production	VQFN (RGZ) 48	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5992
MSP430FR5992IZVWR	Active	Production	NFBGA (ZVW) 87	1000 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	FR5992
MSP430FR59941IPM	Active	Production	LQFP (PM) 64	160 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR59941
MSP430FR59941IPMR	Active	Production	LQFP (PM) 64	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR59941
MSP430FR59941IPN	Active	Production	LQFP (PN) 80	119 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR59941
MSP430FR59941IPNR	Active	Production	LQFP (PN) 80	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR59941
MSP430FR59941IRGZF	Active	Production	VQFN (RGZ) 48	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR59941
MSP430FR59941IRGZT	Active	Production	VQFN (RGZ) 48	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR59941
MSP430FR59941IZVW	Active	Production	NFBGA (ZVW) 87	250 JEDEC TRAY (10+1)	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	FR59941
MSP430FR59941IZVWF	Active	Production	NFBGA (ZVW) 87	1000 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	FR59941
MSP430FR5994IPM	Active	Production	LQFP (PM) 64	160 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5994
MSP430FR5994IPMR	Active	Production	LQFP (PM) 64	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5994
MSP430FR5994IPN	Active	Production	LQFP (PN) 80	119 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5994
MSP430FR5994IPNR	Active	Production	LQFP (PN) 80	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5994
MSP430FR5994IRGZR	Active	Production	VQFN (RGZ) 48	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5994

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						(4)	(5)		
MSP430FR5994IRGZT	Active	Production	VQFN (RGZ) 48	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 85	FR5994
MSP430FR5994IZVW	Active	Production	NFBGA (ZVW) 87	250 JEDEC TRAY (10+1)	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	FR5994
MSP430FR5994IZVWR	Active	Production	NFBGA (ZVW) 87	1000 LARGE T&R	Yes	SNAGCU	Level-3-260C-168 HR	-40 to 85	FR5994

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.